1SS367

Surface Mount SILICON EPITAXIAL SCHOTTKY BARRIER DIODE

1. Features

- Low forward voltage

SOD-323

2. Mechanical Data

- Case:Molded Plastic,SOD-323.
- Epoxy:UL 94V-0 rate flame retardant.
- Terminals:Plated Leads Solderable per MIL-STD-750, Method-2026.
- Marking:S3
- Marking:marked on body.

3. Maximum Ratings

Electrical Characteristics Rating at 25℃ ambient temperature unless otherwise specified.

Characteristic	Symbol	Value	Unit
Maximum (Peak) Reverse Voltage	V_{RM}	15	V
Reverse Voltage	V_R	10	V
Maximum (Peak) Forward Current	I_{FM}	200	mA
Average Forward Current	I_O	100	mA
Surge Forward Current (10 ms)	I_{FSM}	1	A
Power Dissipation	P_D	200	mW
Operating Temperature Range	T_{opr}	-40 to+100	℃
Junction Temperature	T_J	125	℃
Storage Temperature Range	T_{stg}	-55 to+125	℃

4. Electrical Characteristics (T_A=25℃ unless otherwise noted)

Parameters	Symbol	Cindition	Min	TYP	Max	Unit
Forward Voltage	V_F	I_F = 5mA I_F = 100mA	-	-	0.3 0.5	V
Reverse Current	I_R	V_R = 10V	-	-	20	μA
Total Capacitance	C_T	V_R = 0 V, f = 1 MHz	-	-	40	pF

5. Rating And Characteristic Curves

Fig.1 Typical Forward Characteristics

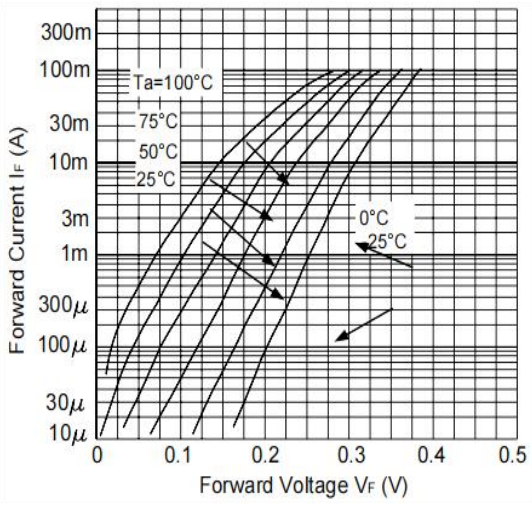


Fig.2 Typical Reverse Characteristics

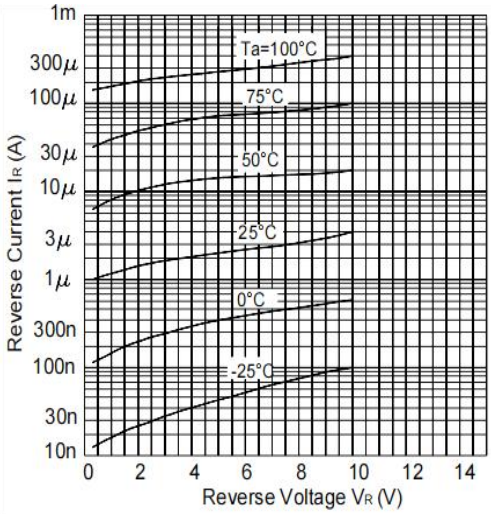


Fig.3 Typ.Total Capacitance vs Reverse Voltage

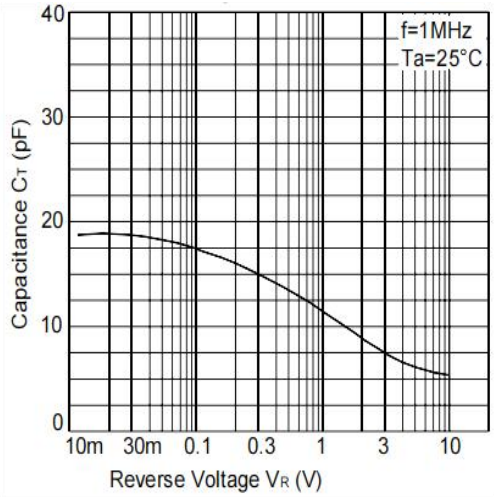
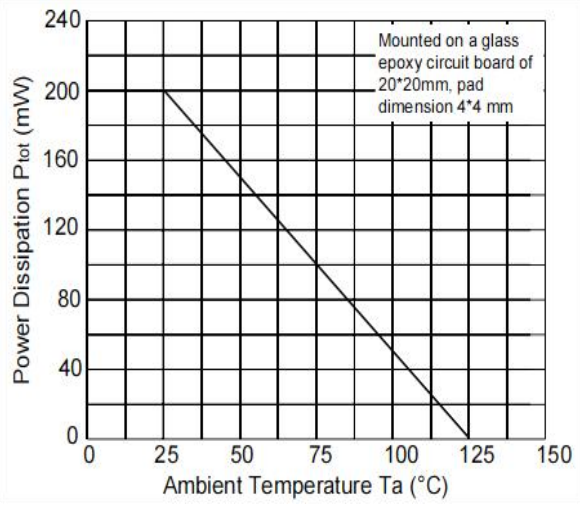
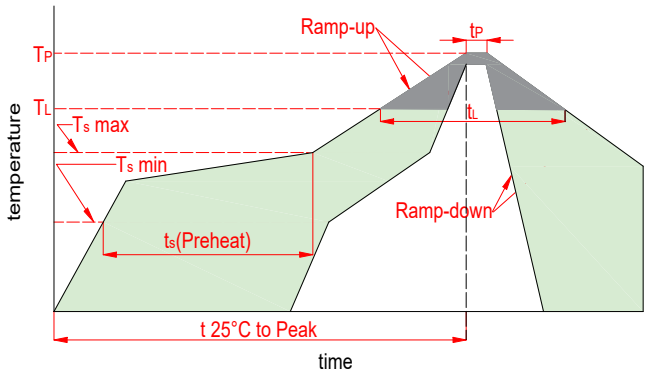


Fig.4 P-Ta

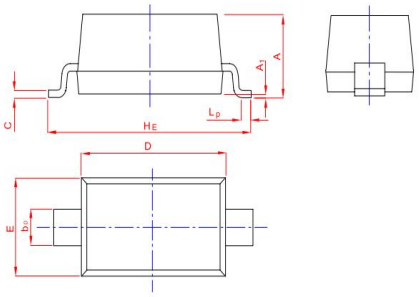


6. Soldering Parameters



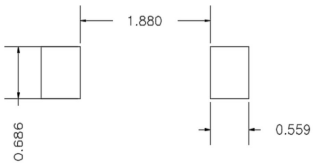
Reflow Condition		Lead-free
Pre Heat	Temp. min(T_s(min))	150℃
	Temp. max(T_s(min))	200℃
	Time(min to max)(t_s)	60~120s
Aver. ramp up rate(Liquidus Temp.)(T_L)to peak		3℃/s max
T_S(max) to T_L-Ramp-up Rate		3℃/s max
Reflow	Temp.(T_L)(Liquidus)	217℃
	Temp.(t_L)(Liquidus)	60~150s
Peak Temp.(T_P)		$260^{+0/-5}$℃
Time within actual peak Temp.(t_p)		30s max
Ramp-down Rate		6℃/s max
Time 25℃ to peak Tempe.(T_p)		8 minutes max
Do not exceed		260℃

7. Dimensions

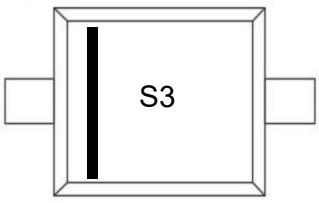


Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.031	0.047	0.800	1.200
bp	0.010	0.016	0.250	0.400
C	0.003	0.006	0.080	0.150
D	0.063	0.071	1.600	1.800
E	0.045	0.055	1.150	1.400
H_E	0.091	0.110	2.300	2.800
A1	0.000	0.004	0.010	0.100
L_P	0.008	0.020	0.200	0.500

Mounting PAD Layout



8. Part Marking System



9. Package Information

Package	Type	Marking Code	Tape Width (mm)	Quantity(pcs)
SOD-323	1SS367	S3	8	3000

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